

WSF40N10

N-Ch MOSFET

General Description

The WSF40N10 is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSF40N10 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

Product Summery

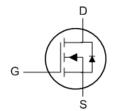
| BVDSS | RDSON | ID |
|-------|-------|-----|
| 100V | 32mΩ | 40A |

Applications

- High Frequency Point-of-Load Synchronous
 Buck Converter
- Networking DC-DC Power System
- Load Switch

TO-252 Pin Configuration





| Symbol | Parameter | Rating | Units |
|-------------------------------------|--|------------|-------|
| V _{DS} | Drain-Source Voltage 100 | | V |
| V _{GS} | Gate-Source Voltage | ±20 | V |
| I _D @T _C =25℃ | Continuous Drain Current, V _{GS} @ 10V ¹ | 40 | А |
| I₀@T₀=100℃ | Continuous Drain Current, V _{GS} @ 10V ¹ | 30 | А |
| I _D @T _A =25℃ | Continuous Drain Current, V _{GS} @ 10V ¹ | 4.2 | А |
| I _D @T _A =70℃ | Continuous Drain Current, V _{GS} @ 10V ¹ | 3.4 | А |
| I _{DM} | Pulsed Drain Current ² | 45 | А |
| EAS | Single Pulse Avalanche Energy ³ | 43.3 | mJ |
| I _{AS} | Avalanche Current | 27 | А |
| P _D @T _C =25℃ | Total Power Dissipation ⁴ | 52.1 | W |
| P _D @T _A =25℃ | Total Power Dissipation ⁴ | 2 | W |
| T _{STG} | Storage Temperature Range | -55 to 150 | °C |
| TJ | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Data

| Symbol | Parameter | Typ. Max. | | Unit | |
|------------------|--|-----------|-----|------|--|
| R _{θJA} | Thermal Resistance Junction-ambient ¹ | | 62 | °C/W | |
| R _{θJC} | Thermal Resistance Junction-Case ¹ | | 2.4 | °C/W | |

Absolute Maximum Ratings



N-Ch MOSFET

Electrical Characteristics (T_J=25⁻¹C, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|--------------------------------------|--|---|------|-------|------|------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V , I _D =250uA | 100 | | | V |
| $\triangle BV_{DSS} / \triangle T_J$ | BVDSS Temperature Coefficient | Reference to 25 $^\circ\!\mathrm{C}$, I_D=1mA | | 0.098 | | V/℃ |
| В | Static Drain-Source On-Resistance ² | V _{GS} =10V , I _D =20A | | 32 | 38 | |
| R _{DS(ON)} | Static Drain-Source On-Resistance | V _{GS} =6.0V , I _D =15A | | 40 | 58 | mΩ |
| V _{GS(th)} | Gate Threshold Voltage | | 2.0 | 3.0 | 4.0 | V |
| $	riangle V_{GS(th)}$ | V _{GS(th)} Temperature Coefficient | $V_{GS}=V_{DS}$, I _D =250uA | | -5.52 | | mV/℃ |
| | Drain Source Lookage Current | $V_{\text{DS}}\text{=}80\text{V}$, $V_{\text{GS}}\text{=}0\text{V}$, $T_{\text{J}}\text{=}25^\circ\!\!\mathrm{C}$ | | | 10 | uA |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =80V , V _{GS} =0V , T _J =55℃ | | | 100 | |
| I _{GSS} | Gate-Source Leakage Current | $V_{GS}=\pm20V$, $V_{DS}=0V$ | | | ±100 | nA |
| gfs | Forward Transconductance | V _{DS} =5V , I _D =20A | | 28.7 | | S |
| Rg | Gate Resistance | V _{DS} =0V , V _{GS} =0V , f=1MHz | | 1.6 | 3.2 | Ω |
| Qg | Total Gate Charge (10V) | | | 60 | 84 | |
| Q _{gs} | Gate-Source Charge | V _{DS} =80V , V _{GS} =10V , I _D =20A | | 9.7 | 14 | nC |
| Q _{gd} | Gate-Drain Charge | | | 11.8 | 16.5 | |
| T _{d(on)} | Turn-On Delay Time | | | 10.4 | 21 | |
| Tr | Rise Time | V_{DD} =50V , V_{GS} =10V , R_{G} =3.3 Ω I _D =20A | | 46 | 83 | |
| T _{d(off)} | Turn-Off Delay Time | | | 54 | 108 | ns |
| T _f | Fall Time | | | 10 | 20 | |
| Ciss | Input Capacitance | V _{DS} =15V , V _{GS} =0V , f=1MHz | | 3848 | 5387 | |
| C _{oss} | Output Capacitance | | | 137 | 192 | pF |
| C _{rss} | Reverse Transfer Capacitance | | | 82 | 115 | 1 |

Guaranteed Avalanche Characteristics

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|--------|--|---|------|------|------|------|
| EAS | Single Pulse Avalanche Energy ⁵ | V _{DD} =25V , L=0.1mH , I _{AS} =15A | 13.4 | | | mJ |

Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|-----------------|--|--|------|------|------|------|
| Is | Continuous Source Current ^{1,6} | $V_G = V_D = 0V$, Force Current | | | 12 | А |
| I _{SM} | Pulsed Source Current ^{2,6} | | | | 45 | А |
| V _{SD} | Diode Forward Voltage ² | V _{GS} =0V , I _S =1A , T _J =25℃ | | | 1.2 | V |
| t _{rr} | Reverse Recovery Time | IF=20A , dl/dt=100A/µs , Tյ=25℃ | | 30 | | nS |
| Q _{rr} | Reverse Recovery Charge | | | 37 | | nC |

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec.

2.The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%

3. The EAS data shows Max. rating . The test condition is $V_{\text{DD}}\text{=}25\text{V}, V_{\text{GS}}\text{=}10\text{V}, \text{L=}0.1\text{mH}, \text{I}_{\text{AS}}\text{=}15\text{A}$

4.The power dissipation is limited by 150 $^\circ\!\!\!\mathrm{C}$ junction temperature

5. The Min. value is 100% EAS tested guarantee.

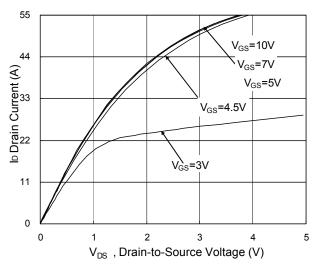
6. The data is theoretically the same as I_{D} and I_{DM} , in real applications , should be limited by total power dissipation.



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Typical Characteristics





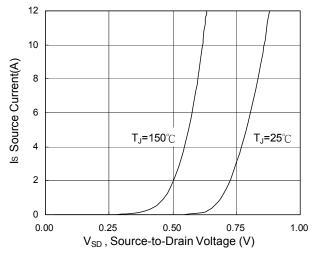
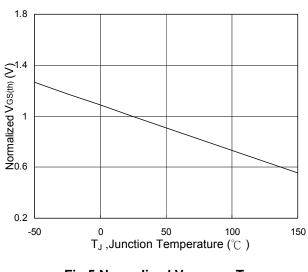


Fig.3 Forward Characteristics Of Reverse





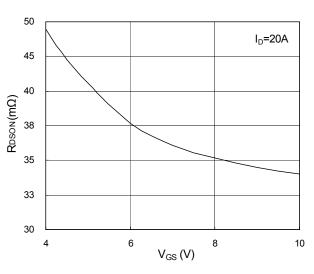


Fig.2 On-Resistance vs. Gate-Source

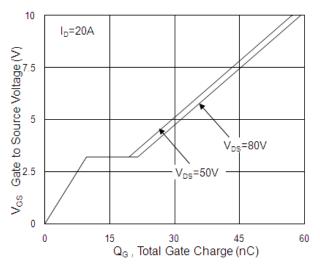
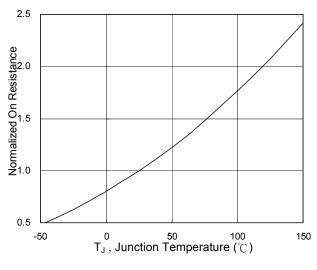


Fig.4 Gate-Charge Characteristics





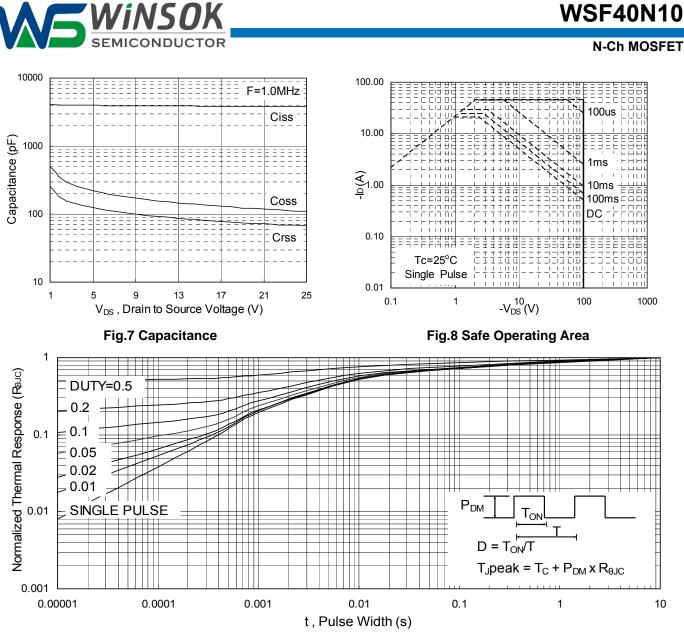


Fig.9 Normalized Maximum Transient Thermal Impedance

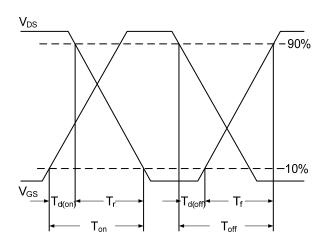


Fig.10 Switching Time Waveform

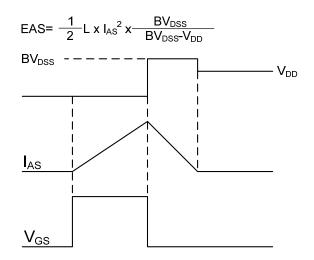


Fig.11 Unclamped Inductive Switching Waveform



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